



Technical Data Sheet

PD 955 M SMT-Adhesive

Description	<p>PD 955 M is a thermosetting single-component, solvent-free polymer adhesive, developed especially for the surface mounting of SMT components onto PCBs and for use on ceramic substrates. The rheology is specially adapted for high-speed-dispensing.</p>												
Key Benefits	<ul style="list-style-type: none"> - Very wide processing window, no tendency towards stringing - Excellent adhesion with standard and also with difficult to glue components - Consistent batch-to-batch quality 		Compliant Products										
Physical Properties	<p style="text-align: center;">Curing</p> <p>The standard curing conditions are: 125°C / 3 minut es. Max. curing temperature should not higher than 200°C.</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="text-align: center;">Temperatur: 100°C</td> <td style="text-align: center;">125°C</td> <td style="text-align: center;">150°C</td> <td style="text-align: center;">180°C</td> </tr> <tr> <td style="text-align: center;">Time: 8 min.</td> <td style="text-align: center;">3 min.</td> <td style="text-align: center;">1,5 min.</td> <td style="text-align: center;">1 min.</td> </tr> </table>		Temperatur: 100°C	125°C	150°C	180°C	Time: 8 min.	3 min.	1,5 min.	1 min.	<p style="text-align: center;">Processing</p> <p>Processing time at 20-30°C max. 2 days</p>	<p style="text-align: center;">Color</p> <p style="text-align: center;">Red</p>	
Temperatur: 100°C	125°C	150°C	180°C										
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Adhesive Conditioning	<p>Remove adhesive from fridge: Before opening the package leave it for 2 hours at room temperature so that adhesive heats up. Do not open cartridge while adhesive is cold to prevent condensation of moisture on the adhesive.</p> <p>Before using adhesive from cartridge: Before inserting nozzle, press small quantity of glue out of cartridge until homogenous glue comes out – during storage of cartridges, low viscosity glue constituents may be found in the tip of the cartridge.</p>												
Application	<p style="text-align: center;">Stencil Printing</p> <p style="text-align: center;"><input type="checkbox"/></p>	<p style="text-align: center;">Screen Printing</p> <p style="text-align: center;"><input type="checkbox"/></p>	<p style="text-align: center;">Dispensing</p> <p style="text-align: center;"><input checked="" type="checkbox"/></p>	<p style="text-align: center;">Dippable</p> <p style="text-align: center;"><input type="checkbox"/></p>	<p style="text-align: center;">PinTransfer</p> <p style="text-align: center;"><input type="checkbox"/></p>	<p style="text-align: center;">Jet</p> <p style="text-align: center;"><input type="checkbox"/></p>							
Cleaning	<p>Before Curing: The adhesive can be removed with Zestron HC or other Zestron and Vigon cleaners. Do not use alcohol as this will cure the adhesive. Cleaned dispensing units should be completely dried before installation.</p> <p>After Curing: Defective components can be replaced by heating (with hot air) the cured adhesive joint above 100 °C. After removing the component (torsion movement), the hot air should be focused on the remaining adhesive in order to remove it with a sharp tool.</p>												
Storage	<p>Store the SMT-adhesive in originally sealed containers and avoid exposure to sunlight and high humidity. Store cartridges with tip pointing downwards!</p> <p>Max expiration date : please refer to the expiry date on the label of the packaged product. Storage conditions in the refrigerator at 2-10°C.</p>												
Contact	<p>www.heraeus-contactmaterials.com</p>		Version	<p>TDS_SMT Adhesive PD955M_20. Nov. 2013</p>									

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